



RELIABILITY REPORT
FOR
MAX3490EESA+
PLASTIC ENCAPSULATED DEVICES

September 24, 2009

MAXIM INTEGRATED PRODUCTS

120 SAN GABRIEL DR.
SUNNYVALE, CA 94086

Approved by
Ken Wendel
Quality Assurance
Director, Reliability Engineering

Conclusion

The MAX3490EESA+ successfully meets the quality and reliability standards required of all Maxim products. In addition, Maxim's continuous reliability monitoring program ensures that all outgoing product will continue to meet Maxim's quality and reliability standards.

Table of Contents

I.Device Description	V.Quality Assurance Information
II.Manufacturing Information	VI.Reliability Evaluation
III.Packaging Information	IV.Die Information
.....Attachments	

I. Device Description

A. General

Devices in the MAX3483E family (MAX3483E/MAX3485E/MAX3486E/MAX3488E/MAX3490E/MAX3491E) are $\pm 15\text{kV}$ ESD-protected, +3.3V, low-power transceivers for RS-485 and RS-422 communications. Each device contains one driver and one receiver. The MAX3483E and MAX3488E feature slew-rate-limited drivers that minimize EMI and reduce reflections caused by improperly terminated cables, allowing error-free data transmission at data rates up to 250kbps. The partially slew-rate-limited MAX3486E transmits up to 2.5Mbps. The MAX3485E, MAX3490E, and MAX3491E transmit at up to 12Mbps. All devices feature enhanced electrostatic discharge (ESD) protection. All transmitter outputs and receiver inputs are protected to $\pm 15\text{kV}$ using IEC 1000-4-2 Air-Gap Discharge, $\pm 8\text{kV}$ using IEC 1000-4-2 Contact Discharge, and $\pm 15\text{kV}$ using the Human Body Model. Drivers are short-circuit current limited and are protected against excessive power dissipation by thermal shutdown circuitry that places the driver outputs into a high-impedance state. The receiver input has a fail-safe feature that guarantees a logic-high output if both inputs are open circuit. The MAX3488E, MAX3490E, and MAX3491E feature full-duplex communication, while the MAX3483E, MAX3485E, and MAX3486E are designed for half-duplex communication.

II. Manufacturing Information

A. Description/Function:	3.3V Powered, $\pm 15\text{kV}$ ESD-Protected, 12Mbps, Slew-Rate-Limited True RS-485/RS-422 Transceivers
B. Process:	B3
C. Number of Device Transistors:	810
D. Fabrication Location:	Oregon
E. Assembly Location:	Thailand, Philippines, Malaysia
F. Date of Initial Production:	April 24, 1999

III. Packaging Information

A. Package Type:	8-pin SOIC (N)
B. Lead Frame:	Copper
C. Lead Finish:	100% matte Tin
D. Die Attach:	Conductive Epoxy
E. Bondwire:	Au (1.0 mil dia.)
F. Mold Material:	Epoxy with silica filler
G. Assembly Diagram:	#05-1901-0257
H. Flammability Rating:	Class UL94-V0
I. Classification of Moisture Sensitivity per JEDEC standard J-STD-020-C	Level 1
J. Single Layer Theta Ja:	170°C/W
K. Single Layer Theta Jc:	40°C/W
L. Multi Layer Theta Ja:	128.4°C/W
M. Multi Layer Theta Jc:	36°C/W

IV. Die Information

A. Dimensions:	146 X 86 mils
B. Passivation:	$\text{Si}_3\text{N}_4/\text{SiO}_2$ (Silicon nitride/ Silicon dioxide)
C. Interconnect:	Al/0.5%Cu with Ti/TiN Barrier
D. Backside Metallization:	None
E. Minimum Metal Width:	3.0 microns (as drawn)
F. Minimum Metal Spacing:	3.0 microns (as drawn)
G. Bondpad Dimensions:	5 mil. Sq.
H. Isolation Dielectric:	SiO_2
I. Die Separation Method:	Wafer Saw

V. Quality Assurance Information

- | | |
|-----------------------------------|---|
| A. Quality Assurance Contacts: | Ken Wendel (Director, Reliability Engineering)
Bryan Preeshl (Managing Director of QA) |
| B. Outgoing Inspection Level: | 0.1% for all electrical parameters guaranteed by the Datasheet.
0.1% For all Visual Defects. |
| C. Observed Outgoing Defect Rate: | < 50 ppm |
| D. Sampling Plan: | Mil-Std-105D |

VI. Reliability Evaluation

A. Accelerated Life Test

The results of the 135°C biased (static) life test are shown in Table 1. Using these results, the Failure Rate (λ) is calculated as follows:

$$\lambda = \frac{1}{\text{MTTF}} = \frac{1.83}{192 \times 4340 \times 80 \times 2} \quad (\text{Chi square value for MTTF upper limit})$$

(where 4340 = Temperature Acceleration factor assuming an activation energy of 0.8eV)

$$\lambda = 13.4 \times 10^{-9}$$

$$\lambda = 13.4 \text{ F.I.T. (60\% confidence level @ 25°C)}$$

The following failure rate represents data collected from Maxim's reliability monitor program. Maxim performs quarterly life test monitors on its processes. This data is published in the Reliability Report found at <http://www.maxim-ic.com/qa/reliability/monitor>. Cumulative monitor data for the B3 Process results in a FIT Rate of 0.51 @ 25C and 8.79 @ 55C (0.8 eV, 60% UCL)

B. Moisture Resistance Tests

The industry standard 85°C/85%RH or HAST testing is monitored per device process once a quarter.

C. E.S.D. and Latch-Up Testing

The RS17-2 die type has been found to have all pins able to withstand a HBM transient pulse of +/-3000 V per Mil-Std 883 Method 3015.7. Latch-Up testing has shown that this device withstands a current of +/-250 mA.

Table 1
Reliability Evaluation Test Results

MAX3490EESA+

TEST ITEM	TEST CONDITION	FAILURE IDENTIFICATION	SAMPLE SIZE	NUMBER OF FAILURES
Static Life Test (Note 1)				
	Ta = 135°C Biased Time = 192 hrs.	DC Parameters & functionality	80	0
Moisture Testing (Note 2)				
HAST	Ta = 130°C RH = 85% Biased Time = 96hrs.	DC Parameters & functionality	77	0
Mechanical Stress (Note 2)				
Temperature Cycle	-65°C/150°C 1000 Cycles Method 1010	DC Parameters & functionality	77	0

Note 1: Life Test Data may represent plastic DIP qualification lots.

Note 2: Generic Package/Process data